PRODUCT DATA SHEET

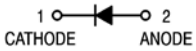
To learn more about JGSEMI, please visit our website at

Datasheet Resources Samples

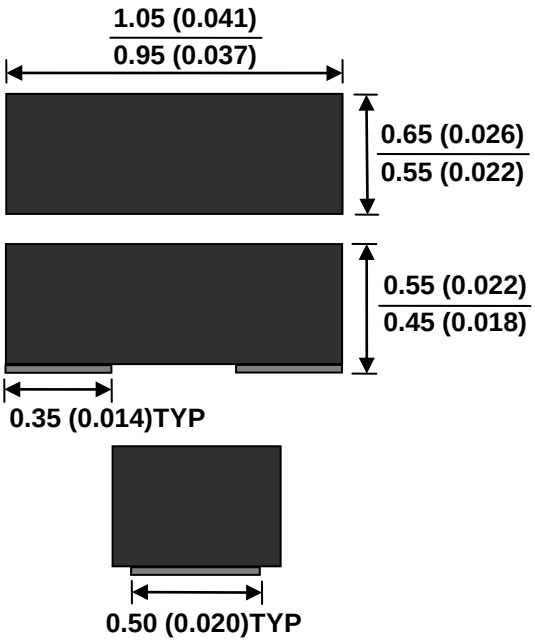
Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO_questions@jgsemi.com.

100mA 30V





DFN1006(0402)



Dimensions in millimeter and (inches)

Features

- Low forward voltage
- Thin & leadless package for space saving
- Pb free version, RoHS compliant, and Halogen free

Mechanical Characteristics

- Case: DFN1006(0402) mold package
- Terminal: Sn/Au plated, solderable per MIL-STD-750, method 2026
- Weight: 0.001 gram(approx.)

Maximum Rating And Electrical Characteristics (at Ta=25℃ unless otherwise noted)

Parameter	Condition	Symbol	Min	Typ	Max	Unit
Repetitive peak reverse voltage		VRRM			35	V
Reverse voltage		VR			30	V
Average forward current		Io			100	mA
Forward current surge peak	8.3 ms single half sine-wave superimposed on rate load (JEDEC method)	IFSM			1	A
Storage/Operation temperature		T_{Sgt}	-40		125	℃
Junction temperature		T_J			125	℃
Forward voltage	IF1=10mA IF2=20mA IF3=100mA	VF			0.29 0.30 0.40	V
Reverse current	VR=30V	IR			30	uA

Typical Characteristics

Fig.1-forward characteristics

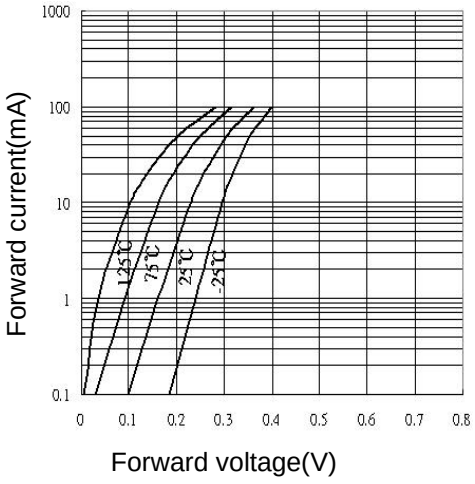


Fig.2-Reverse characteristics

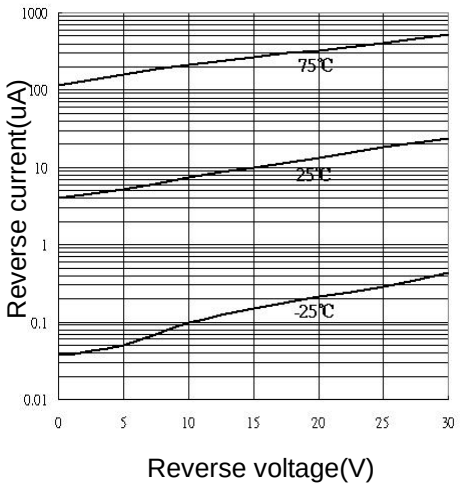


Fig.3 - Capacitance between terminals characteristics

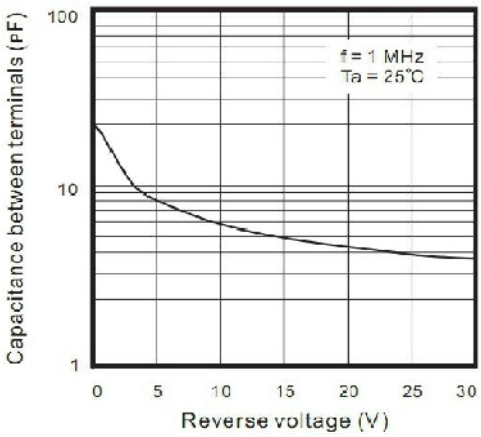


Fig.4 - Current derating curve

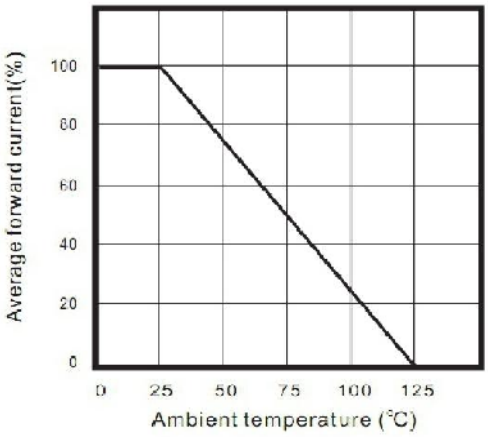


Fig. 5 - VF Dispersion map

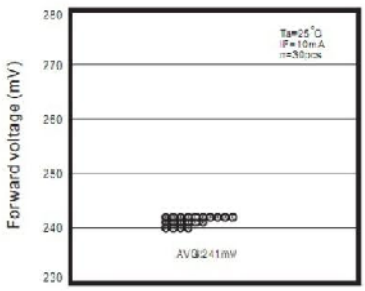


Fig. 6 - IR Dispersion map

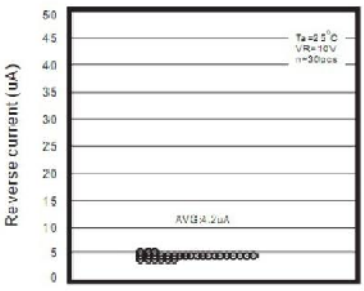
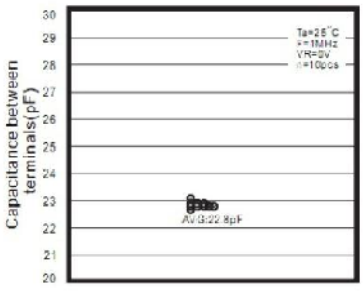


Fig. 7 - CT Dispersion map



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